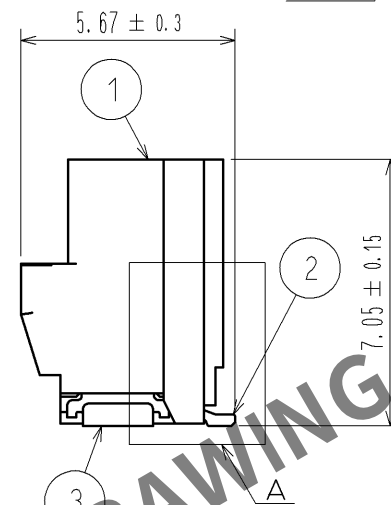
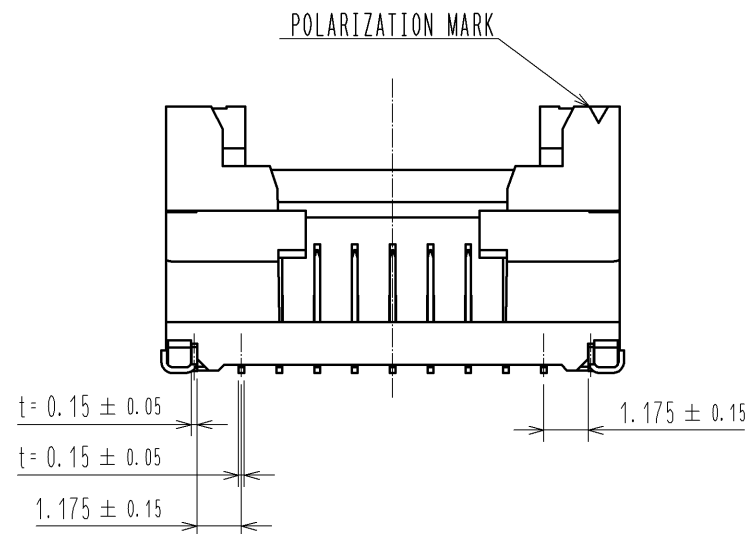
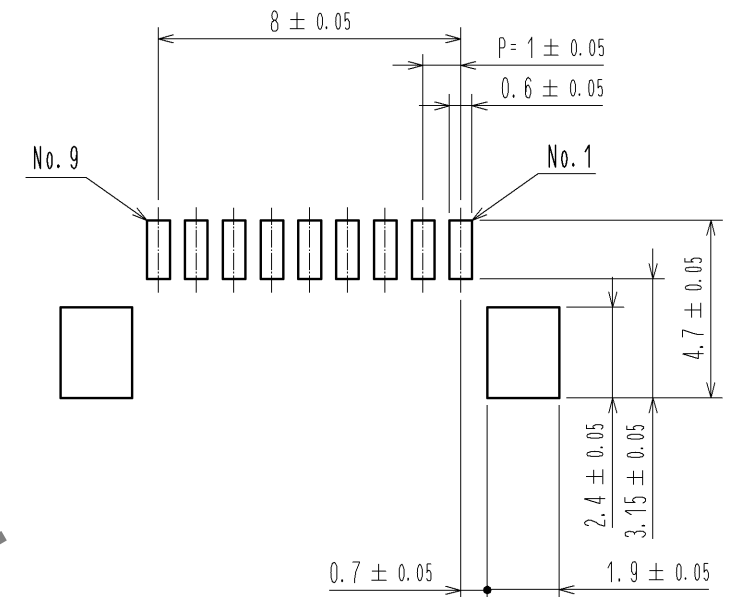
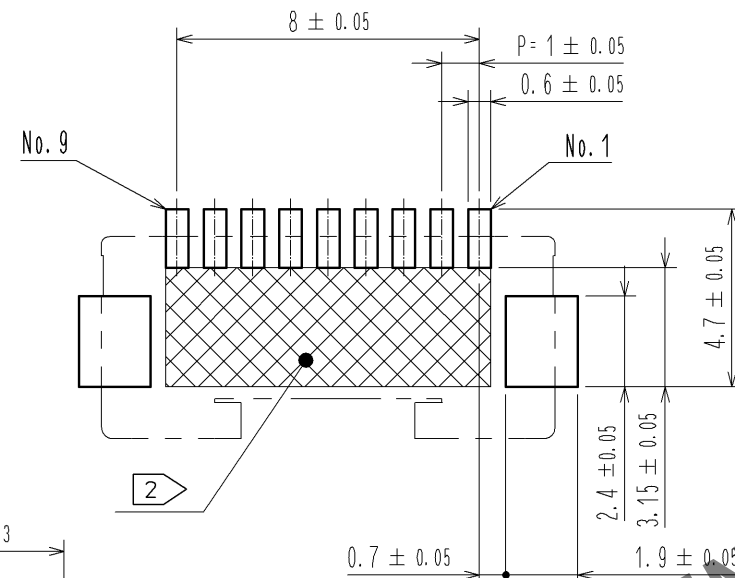
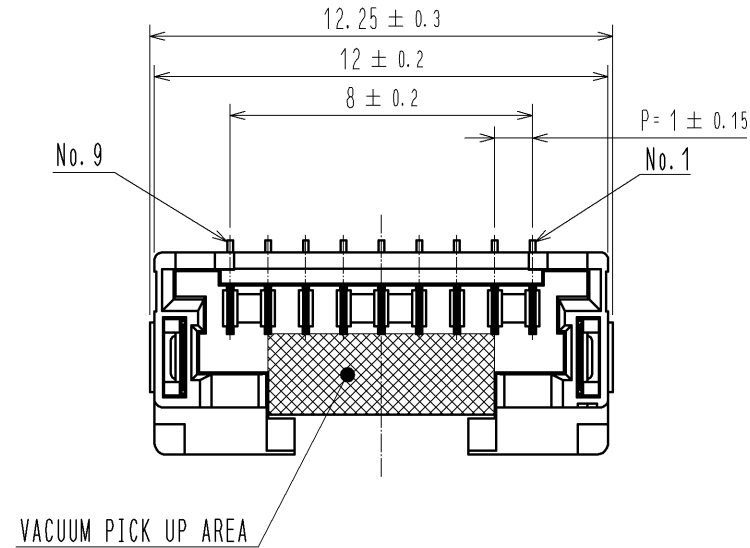


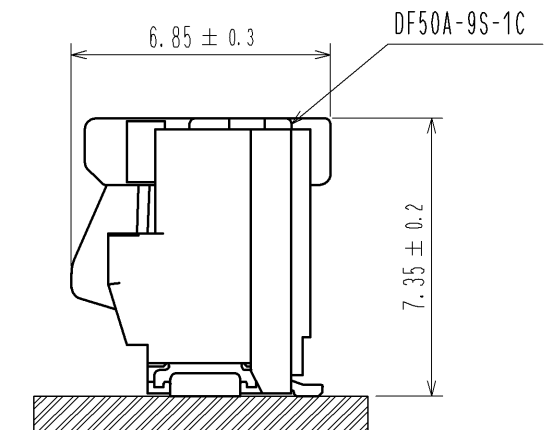
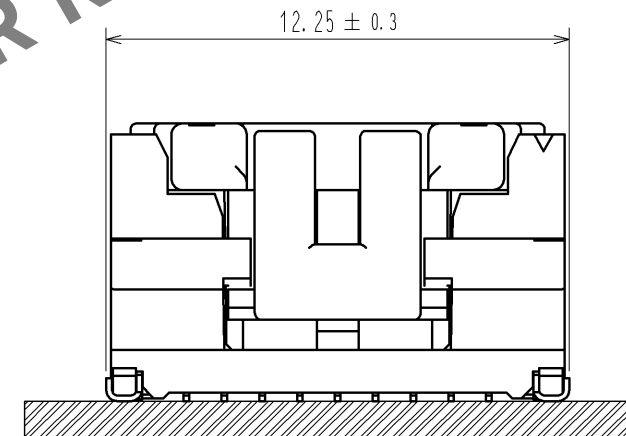
RECOMMENDED PCB LAYOUT
(MOUNTING SURFACE SIDE) (FREE)

RECOMMENDED METAL MASK (FREE)

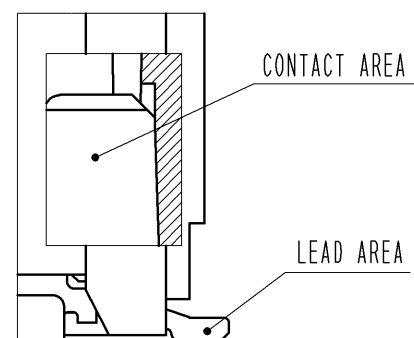
THICKNESS : 0.1mm
OPEN AREA RATIO:100%



MATING FIGURE (5:1)

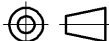


A (10:1)



- NOTES 1. LEAD CO-PLANARITY SHALL BE 0.1mm MAX
2. AREA INDICATED MUST BE FREE OF CONDUCTIVE TRACES OR THE CONDUCTIVE TRACES MUST BE COVERED BY RESIST FILM.
3. PLEASE CONSULT HIROSE WHEN THE PRODUCT IS MOUNTED TO FPC.

3	PHOSPHOR BRONZE	CONTACT AREA : Sn PLATING 1μm MIN UNDER PLATING : Cu PLATING 0.3μm MIN			
2	BRASS	CONTACT AREA : Au PLATING 0.05μm MIN LEAD AREA : Au PLATING 0.05μm MIN UNDER PLATING : Ni PLATING 1μm MIN	6	PS	REEL , BLACK
			5	POLYESTER	CLEAR
1	LCP	BLACK , UL94V-0	4	PS	CLEAR
NO.	MATERIAL	FINISH , REMARKS	NO.	MATERIAL	FINISH , REMARKS

UNITS mm		SCALE 5 : 1	COUNT 	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
HIROSE ELECTRIC CO., LTD.				APPROVED : KI. AKIYAMA	14.10.16	DRAWING NO. EDC3-329668-01	
				CHECED : TS. FUKUSHIMA	14.10.15	PART NO. DF50A-9P-1V(51)	
				DESIGNED : HT. SATO	14.10.15	CODE NO. CL665-1016-0-51	
				DRAWN : MI. SAKIMURA	14.10.15		

	1/2
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